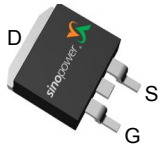
SM7507NSG

N-Channel Enhancement Mode MOSFET

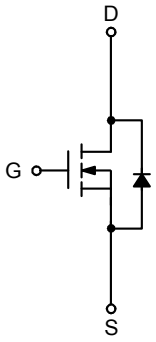
Features

- 75V/170A[a],
  $R_{DS(ON)}$= 4.3mΩ (Max.) @ V_{GS}=10V
- Reliable and Rugged
- Lead Free and Green Devices Available
  (RoHS Compliant)

Pin Description



Top View of TO-263-3



N-Channel MOSFET

Applications

- High Efficiency Synchronous Rectification in SMPS.
- Uninterruptible Power Supply.
- High Speed Power Switching.
- Hard Switched and High Frequency Circuits.

Ordering and Marking Information

SM7507NS □□-□□□ Assembly Material Handling Code Temperature Range Package Code	Package Code G : TO-263-3 Operating Junction Temperature Range C : -55 to 150 °C Handling Code TR : Tape & Reel (800ea/reel) Assembly Material G : Halogen and Lead Free Device
SM7507NS G : SM7507N XXXXX	XXXXX - Lot Code

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines “Green” to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V_{DSS}	Drain-Source Voltage		75	V
V_{GSS}	Gate-Source Voltage		±25	
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	
I_S	Diode Continuous Forward Current	T_C=25°C	80	A
I_D	Continuous Drain Current(Silicon Limited)	T_C=25°C	170[a]	
	Continuous Drain Current(Wire Bond Limited)	T_C=25°C	120[a]	
I_{DM}	Pulsed Drain Current	T_C=25°C	400[b]	
P_D	Maximum Power Dissipation	T_C=25°C	250	W
		T_C=100°C	100	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	0.5	°C/W
I_D	Continuous Drain Current	T_A=25°C	17	A
		T_A=70°C	14	
P_D	Maximum Power Dissipation	T_A=25°C	2.5	W
		T_A=70°C	1.6	
$R_{\theta JA}$*	Thermal Resistance-Junction to Ambient	Steady State	50	°C/W
I_{AS} [c]	Avalanche Current, Single pulse	L=0.5mH	50	A
E_{AS} [c]	Avalanche Energy, Single pulse	L=0.5mH	620	mJ

Note * : Surface Mounted on 1in^2 pad area.
Note a : Bond wire current limit is 120A.
Note b : Pulse width limited by max. junction temperature.
Note c : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_j=25°C).

Electrical Characteristics (T_A = 25°C Unless Otherwise Noted)

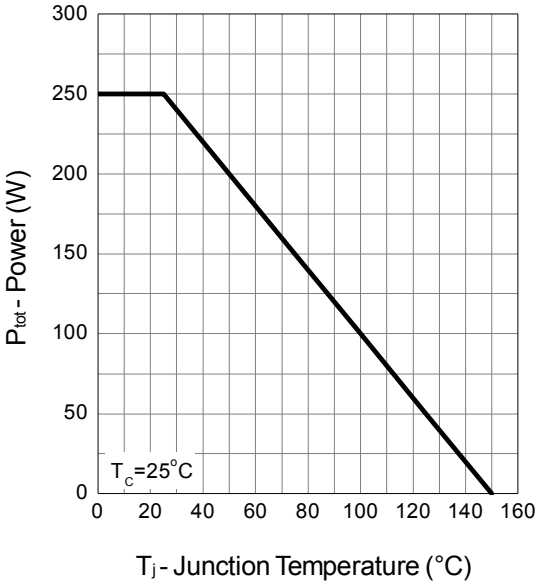
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
B_{VDSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250μA	75	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=60V, V_{GS}=0V	-	-	1	μA
		T_J=85°C	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA	2	3	4	V
I_{GSS}	Gate Leakage Current	V_{GS}=±25V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$ [d]	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=40A	-	3.6	4.3	mΩ
Diode Characteristics						
V_{SD} [d]	Diode Forward Voltage	I_{SD}=20A, V_{GS}=0V	-	0.8	1.3	V
t_{rr}	Reverse Recovery Time	I_{SD}=40A, dI_{SD}/dt=100A/μs	-	52	-	ns
Q_{rr}	Reverse Recovery Charge		-	105	-	nC
Dynamic Characteristics [e]						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,f=1MHz	-	1.2	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=30V, Frequency=1.0MHz	-	5200	6760	pF
C_{oss}	Output Capacitance		-	930	-	
C_{rss}	Reverse Transfer Capacitance		-	255	-	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=30V, R_L=30Ω, I_{DS}=1A, V_{GEN}=10V, R_G=6Ω	-	26	47	ns
t_r	Turn-on Rise Time		-	17	31	
$t_{d(OFF)}$	Turn-off Delay Time		-	88	156	
t_f	Turn-off Fall Time		-	90	162	
Gate Charge Characteristics [e]						
Q_g	Total Gate Charge	V_{DS}=30V, V_{GS}=10V, I_{DS}=40A	-	94	132	nC
Q_{gs}	Gate-Source Charge		-	27	-	
Q_{gd}	Gate-Drain Charge		-	23	-	

Note d：Pulse test; pulse width≤300μs, duty cycle≤2%.

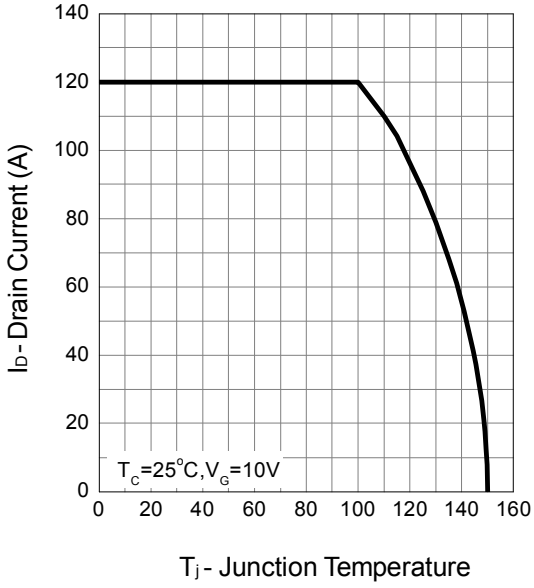
Note e：Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

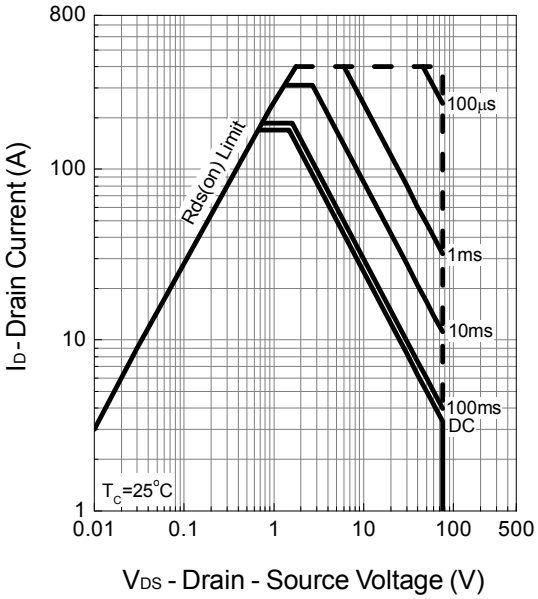
Power Dissipation



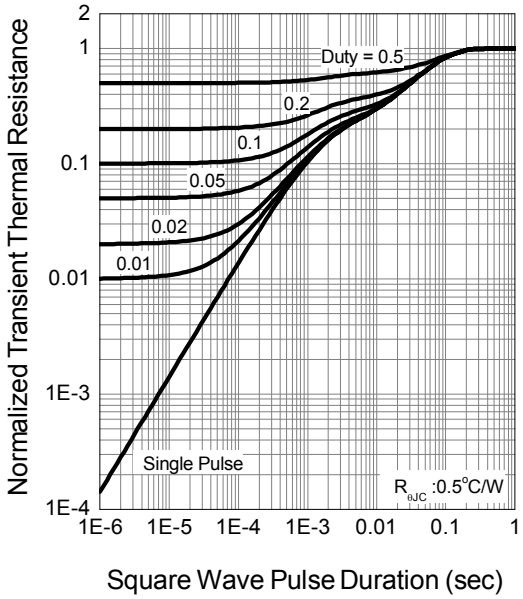
Drain Current



Safe Operation Area

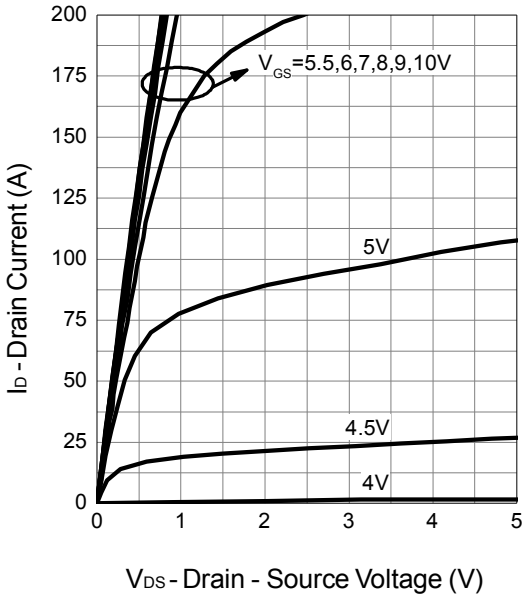


Thermal Transient Impedance

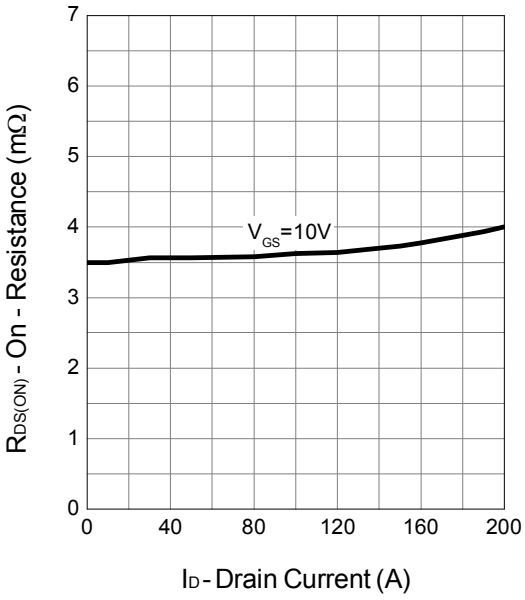


Typical Operating Characteristics (Cont.)

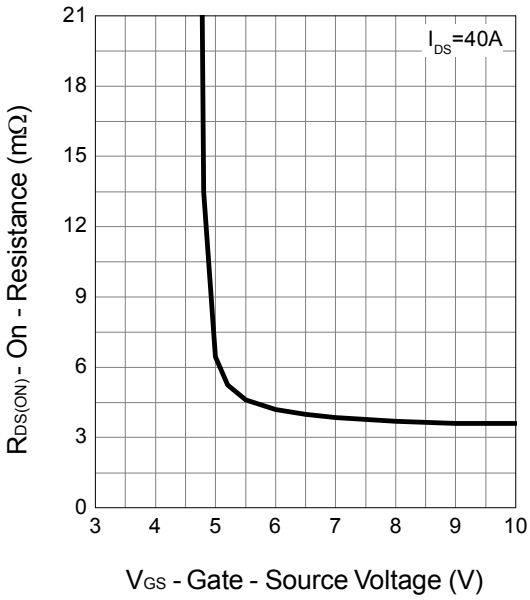
Output Characteristics



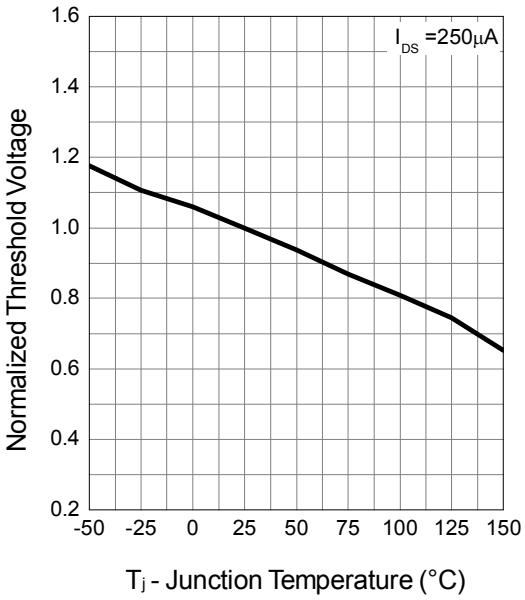
Drain-Source On Resistance



Gate-Source On Resistance

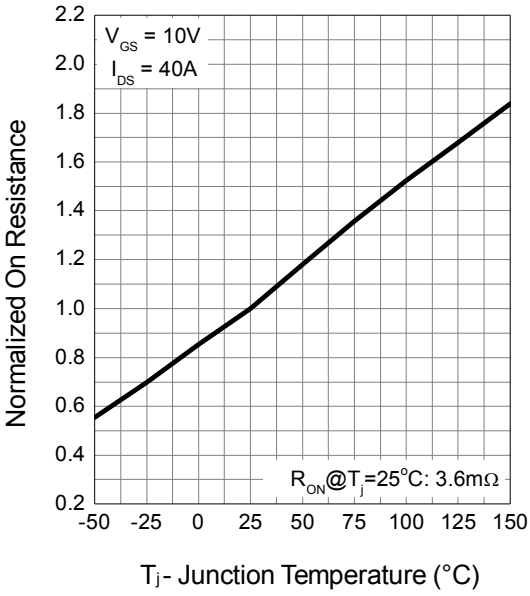


Gate Threshold Voltage

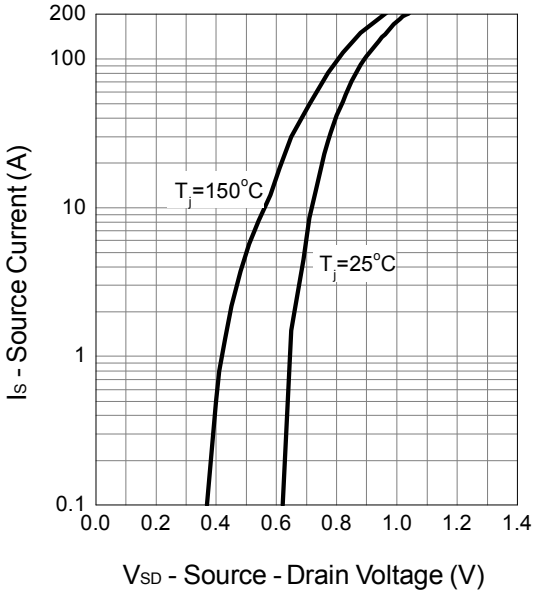


Typical Operating Characteristics (Cont.)

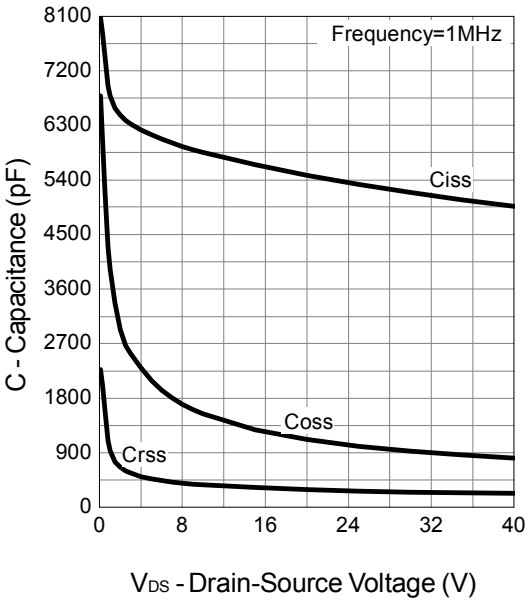
Drain-Source On Resistance



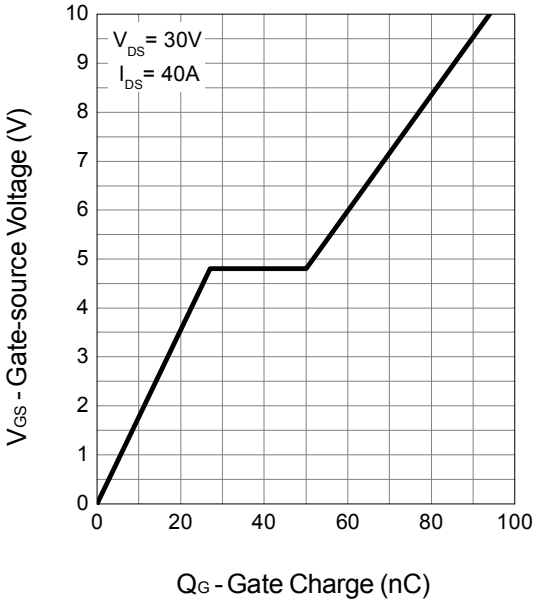
Source-Drain Diode Forward



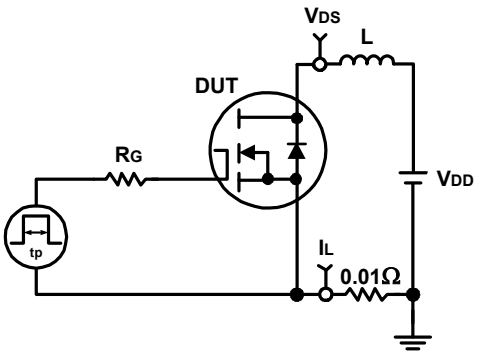
Capacitance

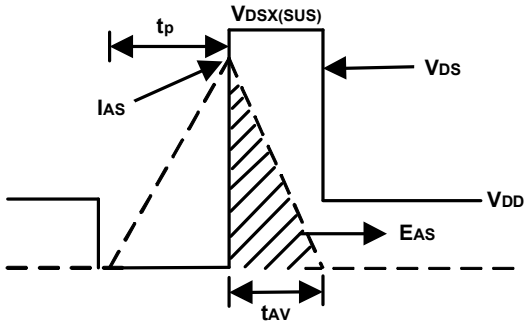


Gate Charge

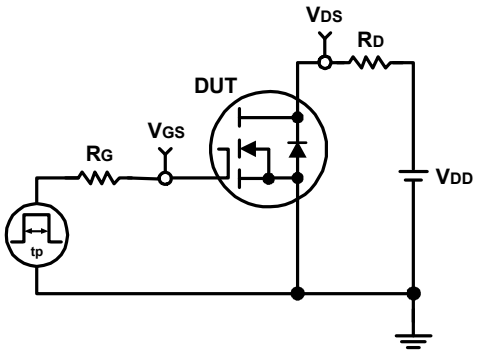


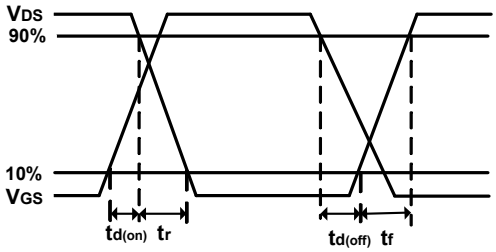
Avalanche Test Circuit and Waveforms





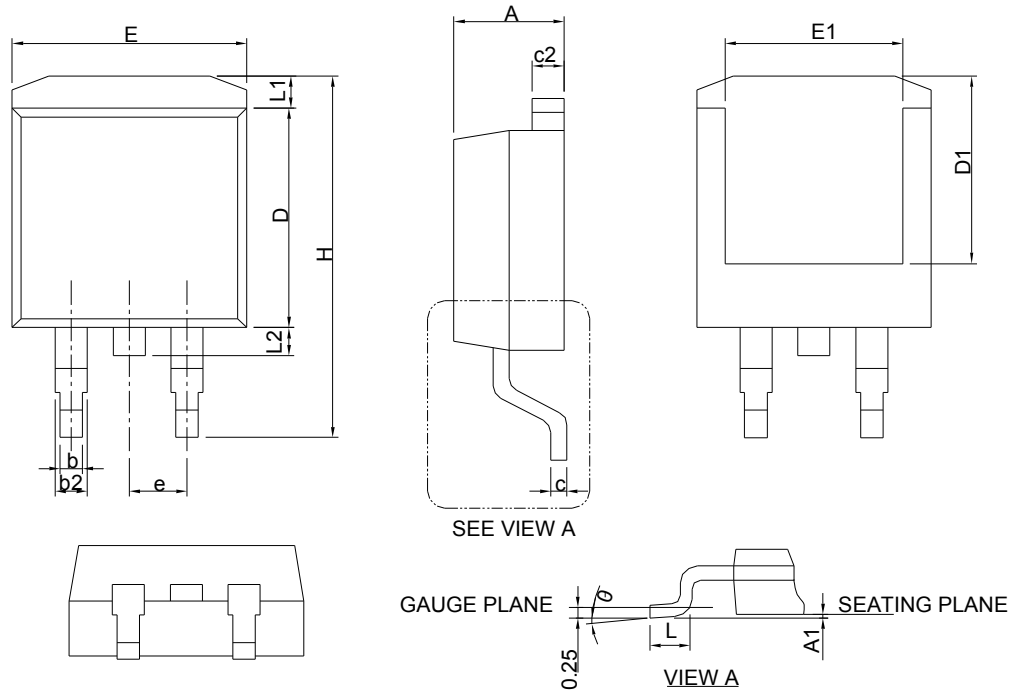
Switching Time Test Circuit and Waveforms





Package Information

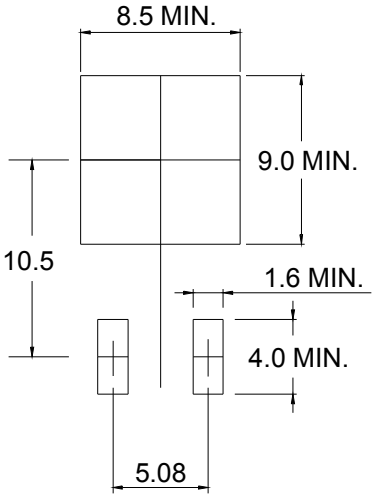
TO-263-3



SYMBOL	TO-263-3			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b2	1.14	1.78	0.045	0.070
c	0.38	0.74	0.015	0.029
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380
D1	6.00	9.00	0.236	0.354
E	9.65	11.43	0.380	0.450
E1	6.22	9.00	0.245	0.354
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.68	-	0.066
L2	-	1.78	-	0.070
θ	0°	8°	0°	8°

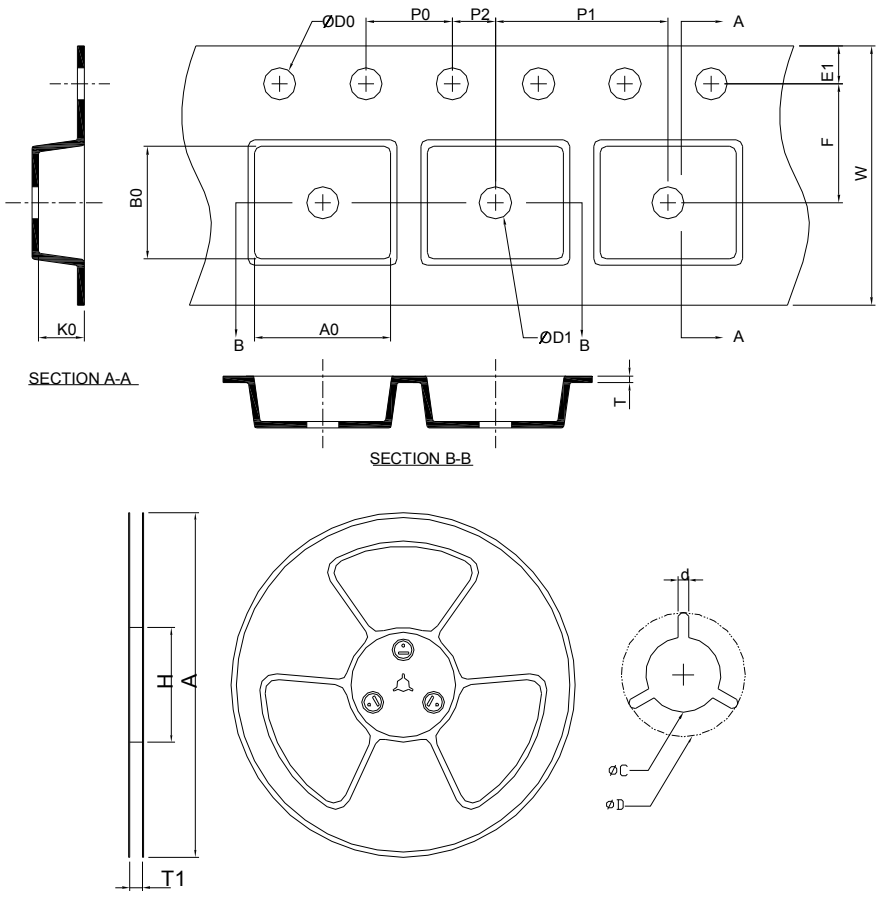
Note : Follow JEDEC TO-263 AB.

RECOMMENDED LAND PATTERN



UNIT: mm

Carrier Tape & Reel Dimensions

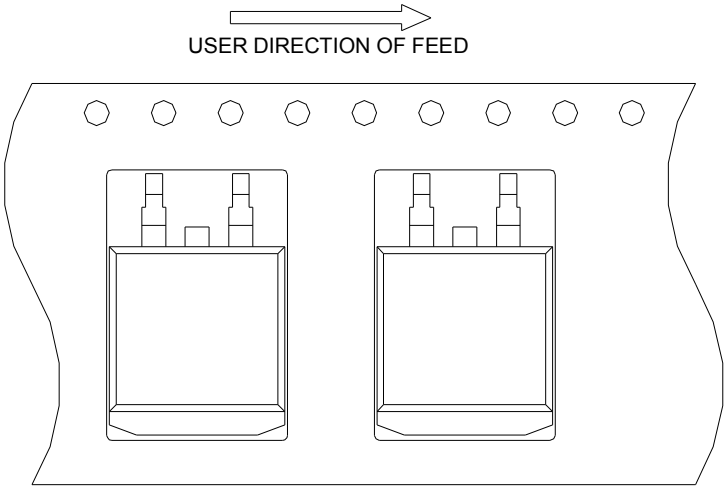


Application	A	H	T1	C	d	D	W	E1	F
TO-263-3	330.0±2.00	50 MIN.	24.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	24.0±0.30	1.75±0.10	11.5±0.10
	P0	**P1**	**P2**	**D0**	**D1**	**T**	**A0**	**B0**	**K0**
	4.0±0.10	16.0±0.10	2.0±0.10	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	10.8±0.20	16.1±0.20	5.2±0.20

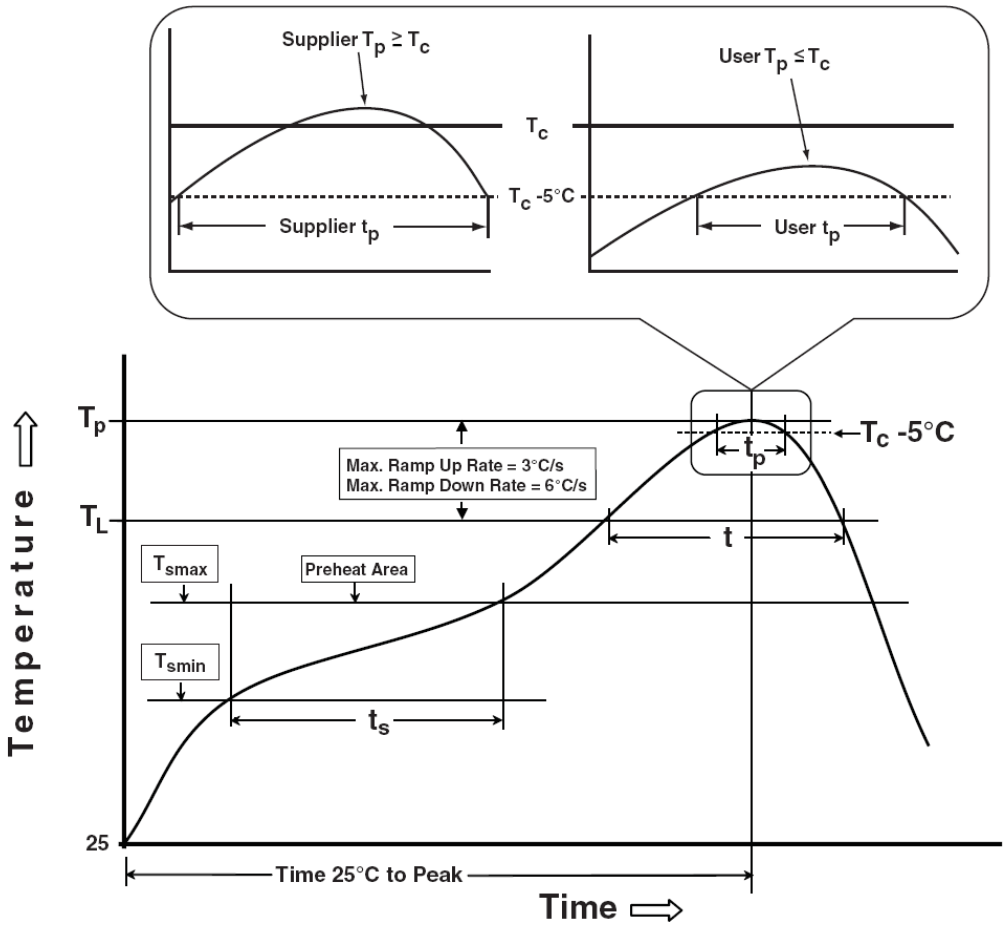
(mm)

Taping Direction Information

TO-263-3



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak Temperature min (T_{smin}) Temperature max (T_{smax}) Time (T_{smin} to T_{smax}) (t_s)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds
Average ramp-up rate (T_{smax} to T_P)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L) Time at liquidous (t_L)	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_P)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ Tjmax
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ Tjmax
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

Customer Service

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